

Abstract

A method for producing a flip-chip mounting electronic component having plural terminals (3) dotted on a mounting face (1) and conductors
5 formed on the terminals (3) realizes flip-chip mounting capable of shortening the distance between bumps (7). To realize this, a step of coating the mounting face (1) with a conductor having a predetermined thickness, a step of masking corresponding positions for the terminal (3) parts on the conductor surface, and a step of removing the conductor except the mask (6)
10 parts are included and performed in this order. The bump is preferably constituted of copper.